

HSF

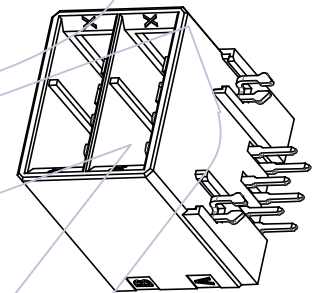
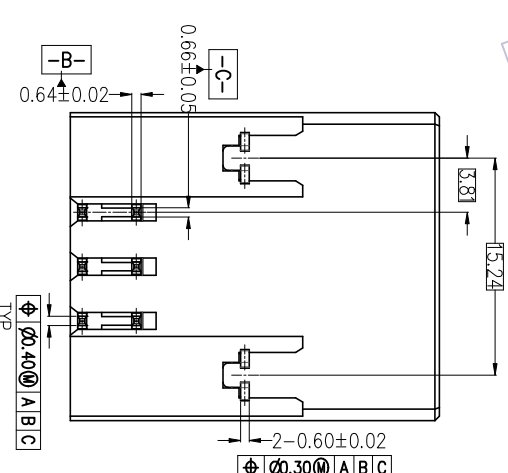
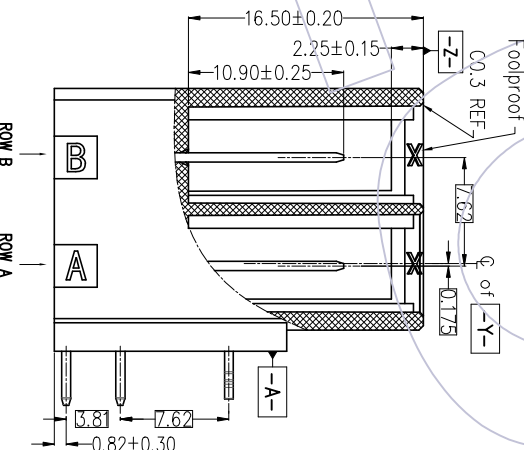
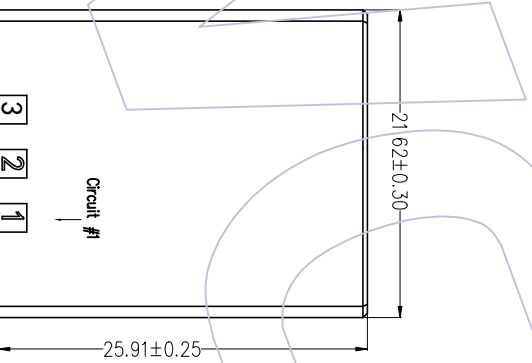
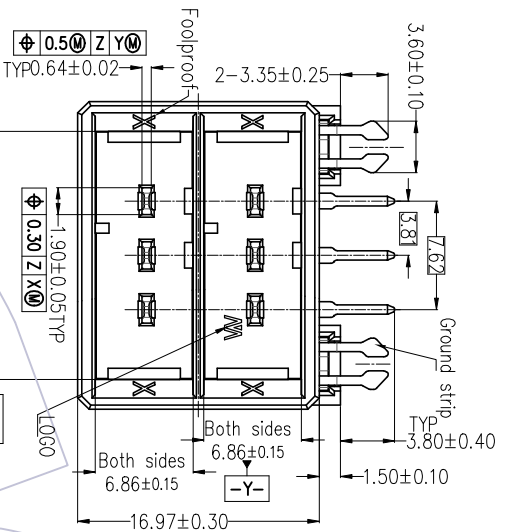
NOTES:

1. Material:
Housing: LCP, G.F. UL94V-0, BK
Contact / strip: Copper Alloy
2. Contact Plating:
xxu" Gold on contact area (See Ordering Information)
100u" Matte tin on solder area,
50u" Nickel underplating overall.
3. Ground strip: 100u" Matte tin over 50u" Nickel.
4. Rated Current: 12.0A Max
5. Contact Resistance: 10mΩ max
6. Withstand Voltage: 1500V AC
7. Insulation Resistance: 1000MΩ min
8. Operation Temperature: -55°C to +105°C
9. Soldering: Solder temperature: 260±5°C
Solder time: 5±1S

Ordering Information

WD3811-2
 2=Double-deck
 WR=90DIP
 No. of pins per row:
 03=3P
 Contact Plated:
 SM=Matte Tin
 W1=3u" Gold/Matte Tin
 W4=15u" Gold/Matte Tin
 W5=30u" Gold/Matte Tin

W=W/T W Logo
 Blank=W/O W Logo
 Foolproof
 04=XX Code
 05=YY Code
 06=XY Code
 A=Troy
 B=Housing Color



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.	TITLE:	WCON-Dornguon	WCON-Kunshan
A0	2020/06/21	NEW	XSR	XX ±0.40	XSR	2020/06/21	mm	A4	WD3811-2WR03XXBAXX(W)	3.81*7.62mm Dyn. (T Type) Double-deck 90DIP with Ground strip	Tel: +86 769 85358920 Fax: +86 769 85358915 E-mail: sales@wcon.com	Tel: +86 512 57468408 Fax: +86 512 57468468 E-mail: sales@wcon.com
				XX ±0.25	CHECK	DATE	1/2				Http: www.wcon.com	
				XXX ±0.15		DATE						
				Angle ± 3'	APPROVE	DATE						
				DIM TOL								

WCON